

What is claimed is:

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1. A mounting socket, comprising:
a socket body having a first side and a second, opposite side, the body having
a plurality of vias extending therethrough;
a plurality of conductive terminals within the vias, wherein the terminals
comprise:
an elastically deformable member.
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2. The mounting socket of claim 1, wherein the elastically deformable member
comprises a spring.
3. The mounting socket of claim 1, wherein the elastically deformable member
comprises a dish spring.
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- Sub B2
4. The mounting socket of claim 1, wherein the elastically deformable member
comprises:
a coil; and
a conductive polymer injected within the vias.
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5. The mounting socket of claim 1, and further comprising:
a first adhesive layer affixed to the first side of the body.
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6. The mounting socket of claim 5, and further comprising:
a polymer tape applied to the first adhesive layer;
a ground and power line circuit laid on the polymer tape; and
a second adhesive layer applied on and protecting the ground and power line
circuit.

7. The mounting socket of claim 5, and further comprising:
a second adhesive layer affixed to the second side of the body.

8. The mounting socket of claim 1, and further comprising:
a push cover attachable to the socket body first and second sides.

Suba2> 9. A method of mounting a socket to a board, comprising:
applying an adhesive layer to a board side of the socket;
leveling the adhesive layer to make the adhesive layer substantially coplanar
with contact terminals of the socket; and
adhering the socket to the board.

10. The method of claim 9, and further comprising:
applying a second adhesive layer to a package side of the socket opposite the
board side of the socket; and
adhering a package to the second adhesive layer.

Suba3> 11. A method of mounting a package to a board using a socket having contact
terminals, the method comprising:
applying a first adhesive layer to a first, package side of the socket;
leveling the first adhesive layer to make the adhesive layer substantially
coplanar with the contact terminals;
adhering the package to the first adhesive layer;
applying a second adhesive layer to a second, board side of the socket;
leveling the second adhesive layer to make the second adhesive layer
substantially coplanar with the contact terminals; and
adhering the board to the second adhesive layer.

12. A circuit interconnect, comprising:
a circuit board carrier having a plurality of through holes formed therein; and
a plurality of conductive terminals with lands at each end, each terminal in
one of the through holes, wherein each conductive terminal comprises
an elastically deformable member.

13. The circuit interconnect of claim 12, and further comprising:
a first adhesive layer affixed to a first side of the circuit board carrier, the first
layer having openings to expose the lands.

14. The circuit interconnect of claim 13, and further comprising:
a second adhesive layer affixed to a second side of the circuit board carrier,
the second layer having openings to expose the lands, the second side
opposite the first side.

15. The circuit interconnect of claim 12, wherein the conductive terminals are
conductive rubber.

16. The circuit interconnect of claim 12, wherein the conductive terminals
comprise a spring.

17. The circuit interconnect of claim 12, wherein the conductive terminals
comprise:
a compressible coil; and
a conductive polymer injected within the vias.

18. A circuit package, comprising:
a substrate having a plurality of conductive terminals therethrough;

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a first adhesive layer affixed to a first side of the substrate; and
a package affixed to the first adhesive layer.

19. The circuit package of claim 18, and further comprising:
5 a second adhesive layer affixed to a second side of the substrate, the second side opposite the first side.

Sub 25

20. An integrated circuit, comprising:
a substrate having a plurality of vias therein; and
10 a plurality of elastically deformable terminals, each terminal positioned in a via.

21. A circuit assembly, comprising:
a substrate having a built-in socket, the socket having a plurality of vias
15 therein;
a plurality of elastically deformable, conductive terminals, each terminal within a via;
a circuit board having a plurality of mounting areas, the mounting areas in a plurality of planes which are substantially non-planar with each other;
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wherein each terminal is individually deformable to contact its respective mounting area at the plane of the mounting area.

22. A circuit assembly, comprising:
a microprocessor;
a substrate having a built-in socket having a plurality of vias therein, and a
plurality of conductive, elastically deformable terminals, at least a
portion of the plurality of terminals within a via; and

a motherboard having a plurality of mounting areas thereon, each elastically deformable terminal deformed to contact a mounting area.

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